

Electronic Patent Application Fee Transmittal

Application Number:	10509895			
Filing Date:	01-Oct-2004			
Title of Invention:	Method for severing brittle material substrate and severing apparatus using the method			
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Filer:	Lee Cheng			
Attorney Docket Number:	APA-0217			
Filed as Small Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	2251	1	65	65

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				65